Die Attach Process

Process Technology
Epoxy, Eutectic, Soft Solder ,WBC Die Attach

State of Art Die Attach Machine & Process

- Premium automotive grade die attach materials
- High performance pick and place
- Auto-adjusting pick-up tool offsets and dispense pressure after syringe change.
- Able to handle Wafer Size: 4” - 12”
- Die Size: 0.5 - 20 mm
- Die Thickness: > 0.075 mm
- Pre-bond, post bond inspection quality checks
- Die Shear monitoring with Dage Shear Tools